nepes hayyim

*** Material Composition -nRF52820-CFAA-D**
Drawing #- D005222_A

Material	Purpose	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogenous material	PPM	% weight of substance per package
Polybenzoxazole1	Dielectric	Proprietary	----------	0.04664	100%	7205	0.721%
Polybenzoxazole2	Dielectric	Proprietary	----------	0.04338	100%	6701	0.670%
RDL Seed Layer	Seed Layer	Ti	7440-32-6	0.00050	4.64%	77	0.008%
	Seed Layer	W	7440-33-7	0.00447	41.73%	690	0.069%
	Seed Layer	Cu	7440-50-8	0.00574	53.63%	887	0.089%
Copper	Interconnect	Cu	7440-50-8	0.11479	100%	17732	1.773%
UBM Seed Layer	Seed Layer	Ti	7440-32-6	0.00017	4.64%	27	0.003%
	Seed Layer	W	7440-33-7	0.00156	41.73%	240	0.024%
	Seed Layer	Cu	7440-50-8	0.00200	53.63%	309	0.031%
Copper	UBM	Cu	7440-50-8	0.08999	100%	13902	1.390%
Solder Ball	Interconnect	Sn	7440-31-5	1.34464	95.50%	207719	20.772%
	Interconnect	Ag	7440-22-4	0.05632	4.00%	8700	0.870%
	Interconnect	Cu	7440-50-8	0.00704	0.50%	1088	0.109%
Die	Circuit	Si	7440-21-3	4.52366	100%	698812	69.881%
Top Surface Laminate	Mark Surface	Proprietary	----------	0.23247	100%	35912	3.591%
			Package Weight (mg):	6.47		% Total:	100%

*NOTE : ** LC2850 is not used for this device at nepes hayyim Corporation.*